Abstracts

In-circuit testing of complex circuits using on-wafer probing and electromagnetic coupled ground interconnects

J. Kassner and W. Menzel. "In-circuit testing of complex circuits using on-wafer probing and electromagnetic coupled ground interconnects." 2000 MTT-S International Microwave Symposium Digest 00.3 (2000 Vol. III [MWSYM]): 1863-1866.

With increasing complexity, testing of the different functions of integrated microwave and mm-wave circuits gets increasingly difficult. A method is presented to perform in-circuit testing of different circuits and components either on a common substrate or on different substrates on a common carrier. Stubs are used to provide RF ground for on-wafer testing. Between the circuits on a common substrate, gaps are introduced which are closed by bond ribbons after testing. The method is tested for the examples of the combination of microstrip lines, one GaAs and one alumina and of the combination of a low and a high pass filter on a common substrate.

❑ Return to main document.